

Title (en)

PHOTOSENSITIVE RESIN COMPOSITION, PHOTOSENSITIVE ADHESIVE FILM, AND LIGHT-RECEIVING DEVICE

Title (de)

LICHTEMPFLINDLICHE HARZZUSAMMENSETZUNG, LICHTEMPFLINDLICHE HAFTFOLIE UND LICHTAUFNEHMENDE VORRICHTUNG

Title (fr)

COMPOSITION DE RÉSINE PHOTOSENSIBLE, FILM ADHÉSIF PHOTOSENSIBLE ET DISPOSITIF DE RÉCEPTION DE LUMIÈRE

Publication

EP 2352065 A1 20110803 (EN)

Application

EP 09824904 A 20091105

Priority

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Abstract (en)

A photosensitive resin composition includes (A) an alkali-soluble resin, (B) an epoxy resin, and (C) a photopolymerization initiator, the epoxy resin (B) being an epoxy resin having a naphthalene skeleton and/or an epoxy resin having a triphenylmethane skeleton. A semiconductor device including a semiconductor wafer, a transparent substrate, and a spacer formed by a photosensitive adhesive film produced using the photosensitive resin composition does not suffer from condensation of dew. A light-receiving device having excellent reliability can also be obtained.

IPC 8 full level

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CPC (source: EP KR US)

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